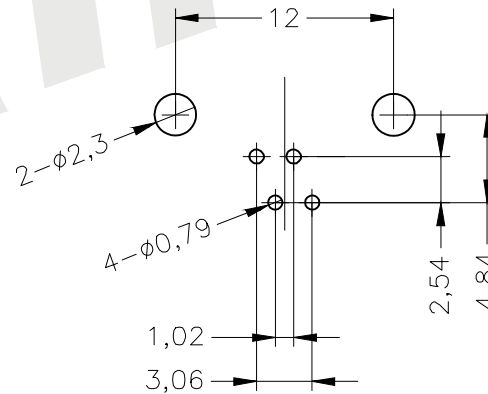
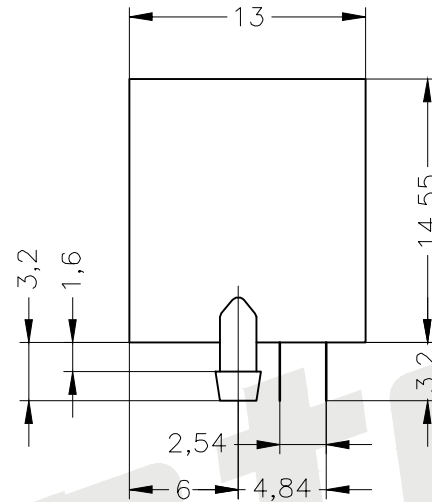
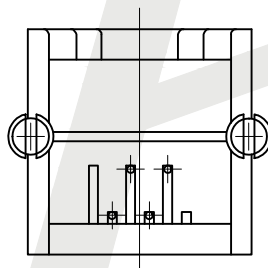
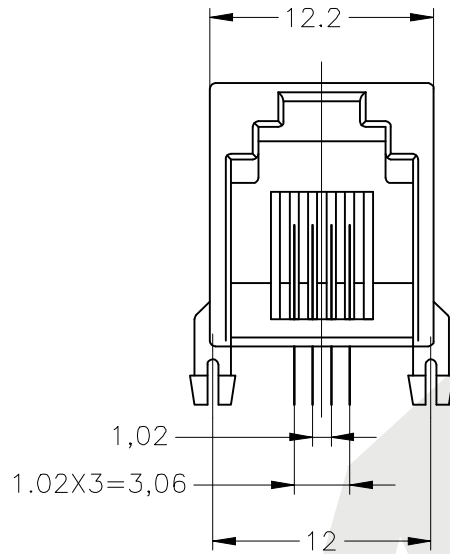


HSF



PCB LAYOUT

NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE $t=0.3\text{mm}$
3. PLATING: SELECTING GOLD PLATING $1\mu \sim 50\mu$ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATIN. OVER NICKEL IN SOLDER AREA
4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE

ELECTRICAL

1. VOLTAGE RATING: 125VAC RMS
2. CURRENT RATING: 1.5AMP
3. CONTACT RESISTANCE: 30MILLIOHMS MAX
4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTTON PRB-SOLDER: 1 LB MIN

REVIORNMENTAL

1. STORAGE: -40°C TO 85°C
2. OPERATION: 0°C TO 70°C

Order code:

ATRJ5521 — 6P — 4C — X — A

- | | | | | |
|------------------------------------|---|---|---|-------------------|
| ① | ② | ③ | ④ | ⑤ |
| ① SERIES NO: | | | | ⑤ Shield |
| ② NUMBER OF POSITIONS (8P, 6P, 4P) | | | | A: W/0 Shield |
| ③ NUMBER OF CONTACTS (8C, 6C, 4C) | | | | B: Half Shield |
| ④ Contact Plating | | | | C: Shield W/Eml |
| | | | | D: Shield W/0 Eml |
| | | | | G0: Gold flash |
| | | | | G1: 3U" Gold |
| | | | | G2: 5U" Gold |
| | | | | G3: 10U" Gold |
| | | | | G4: 15U" Gold |
| | | | | G5: 30U" Gold |
| | | | | SN: Tin |

Unless Otherwise specified tolerance
 X. ±0.35 X.XX: ±0.20
 X.X: ±0.25 X.XXX: ±0.15

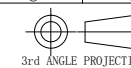
Antenk® ANTENK ELECTRONICS CO., LTD
[Http://www.antenk.com](http://www.antenk.com)
 E-mail: sales@antenk.com

SCALE: As Shown	UNIT: mm
DRAW Wu Feng Rong	DATE 05/09/2019
CHECK BobYang	DATE 05/09/2019

TITLE: RJ11 Jack side entry,
Full plastic, withuot panel

DRAWING NO: ATRJ5521-6P4C-X-A

PRODUCT NO: ATRJ5521-6P4C-X-A



REV	DESCRIPTION	DATE
1		
2		
3		
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